

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

5 Claim 1 (currently amended): An integrated circuit package ~~having central leads comprising:~~

a substrate having an upper surface, a lower surface and a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is forming-formed with a wiring regions arranged at the two sides one side of the long slot, and the wiring regions is formed forming with a plurality of eonnected
10 connection points, and a the length of the wiring regions are-is smaller than a length of the long slot of the substrate;

a resistant layer 42, which is coated on and in contact with the lower surface54 of the substrate40, and is located between the long slot56--and the wiring region58, wherein the resistant layer separates the long slot from the
15 wiring region, and a length of the resistant layer is substantially equal to the length of the wiring region;

a glue layer being-coated on the upper surface of the substrate and being located at ~~the~~ a periphery of the long slot;

an integrated circuit having a first surface ~~forming-formed~~ with a plurality of
20 bonding pads and a second surface, the first surface being adhered to the glue layer, ~~then-the~~ bonding pads being exposed from the long slot of the substrate;

a plurality of wires, each of which is arranged within the long slot of the substrate and ~~is electrically connects eonnected-the~~ bonding pad of the integrated circuit to the ~~eonnected-connection~~ point of the substrate; and

25 a first compound layer being-filled within the long slot of the substrate for ~~protecting to protect~~ the each-wires.

Claim 2 (cancelled).

Claim 3 (currently amended): The integrated circuit package ~~having central-~~
~~leads according to claim 1, wherein the eonnected-connection points of the lower~~
30 ~~surface of the substrate is-are~~ formed with a ball grid array (BGA).

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Claim 4 (currently amended): The integrated circuit package having central leads according to claim 1, wherein further comprises ~~comprising~~ a second compound layer, which ~~is covered on~~ covers the upper surface of the substrate.